

FIG. 1

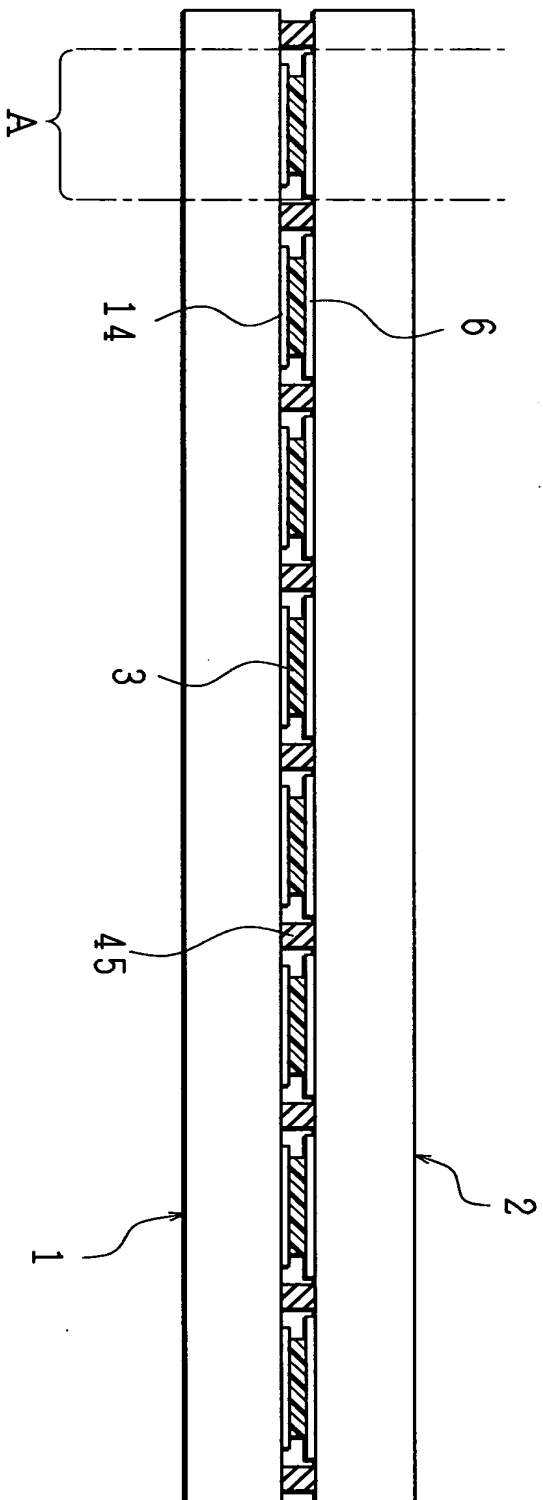


FIG. 2

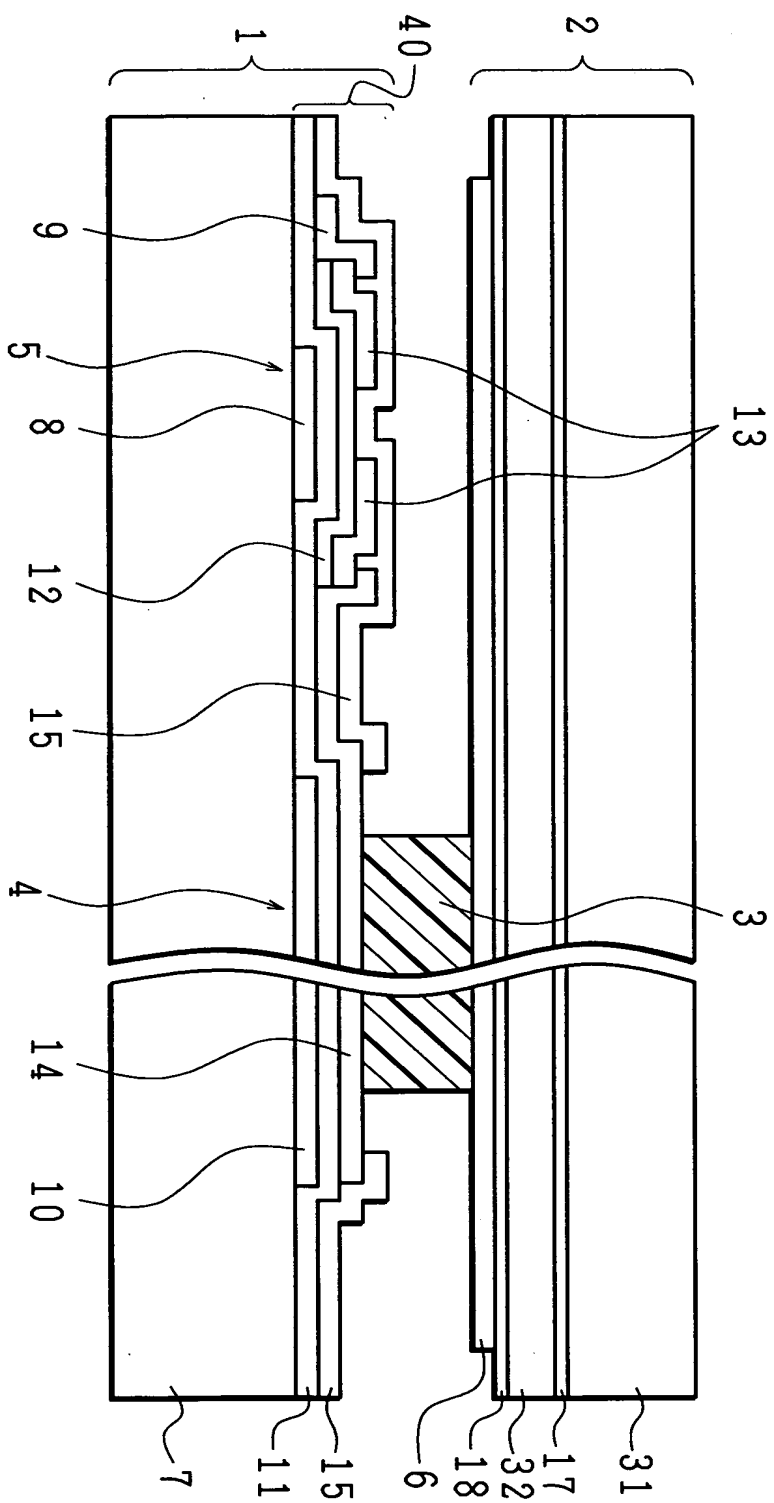


FIG. 3

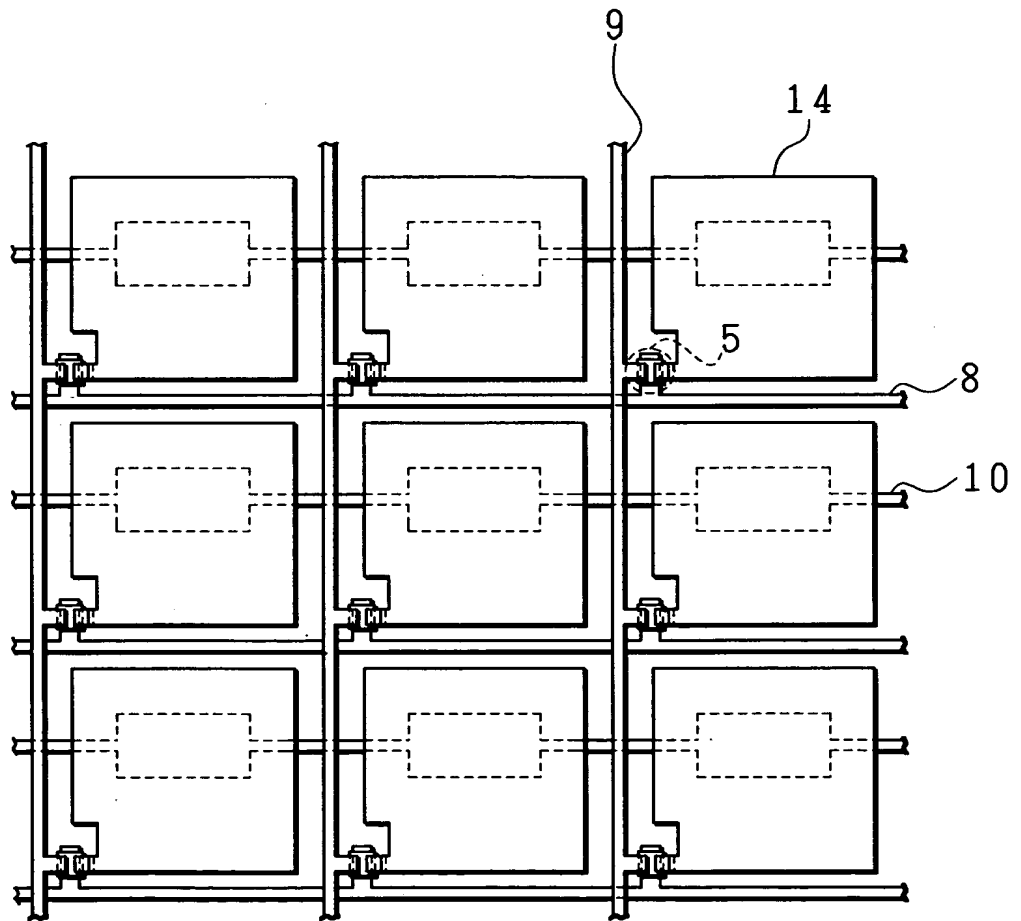
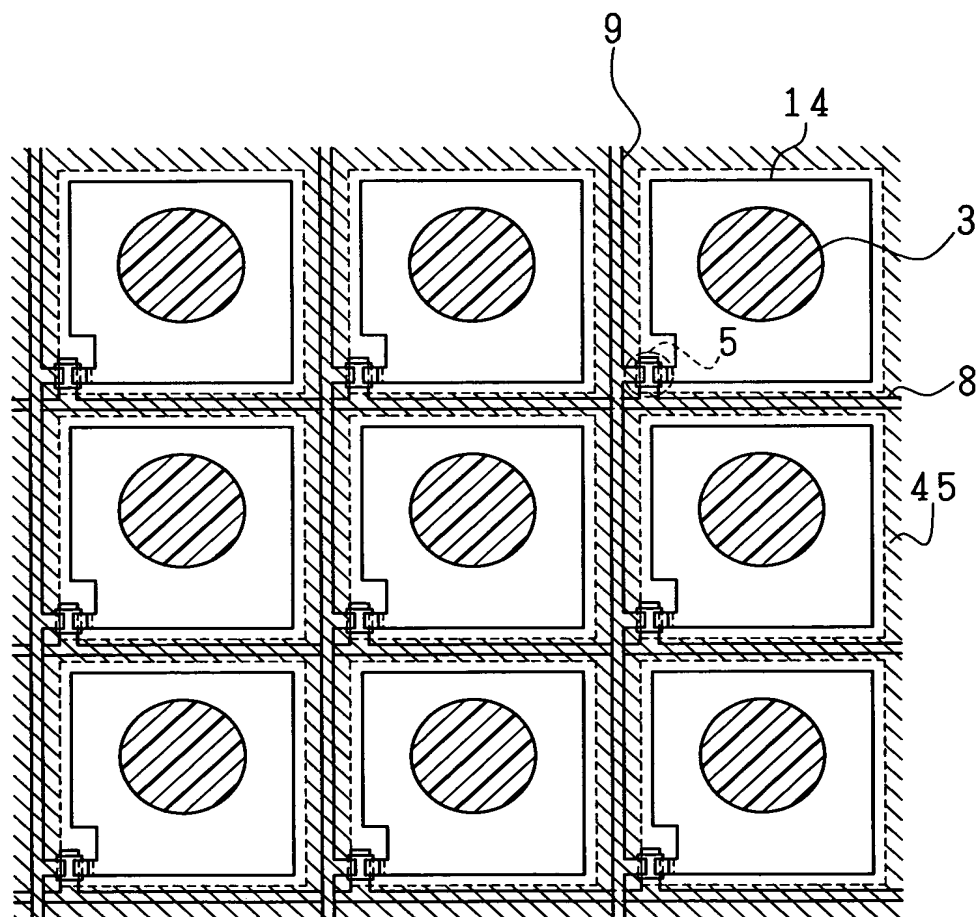


FIG. 4



(Cs ELECTRODES 10 ARE OMITTED)

FIG. 5

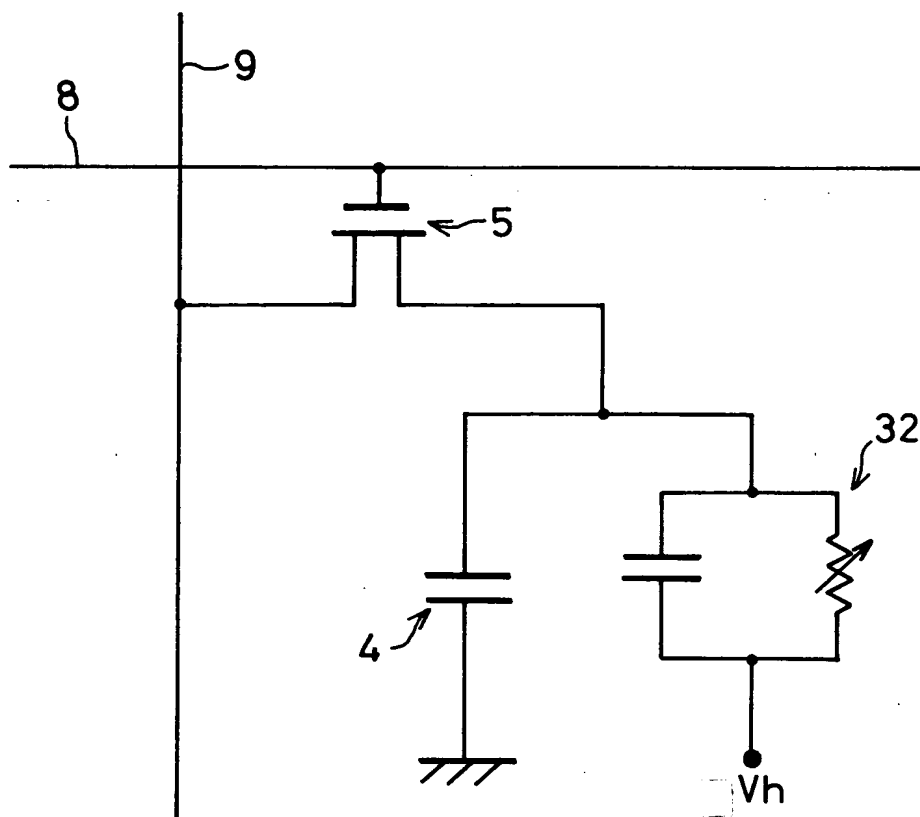


FIG. 6 (a)

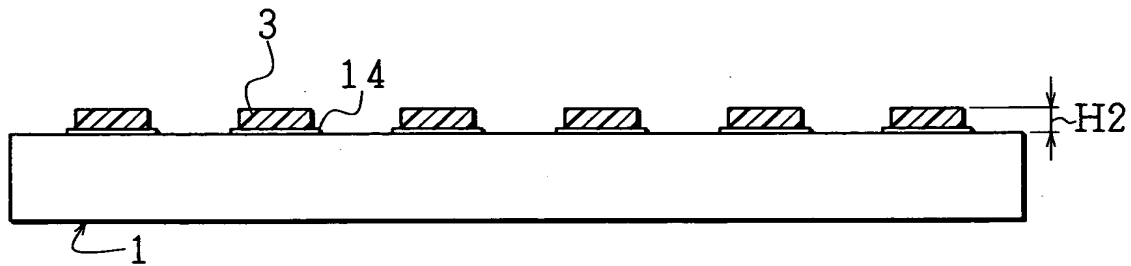
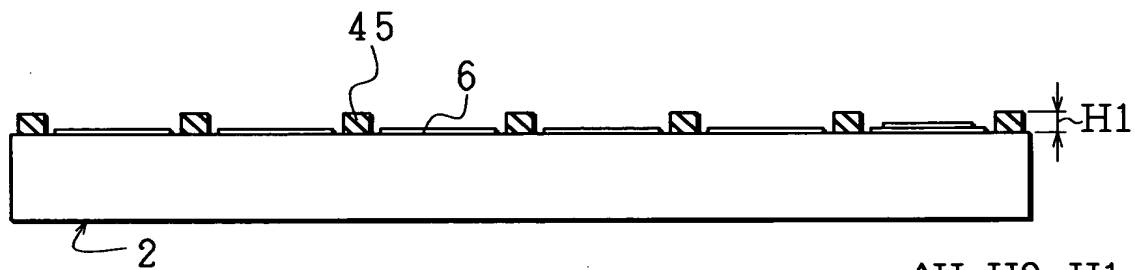


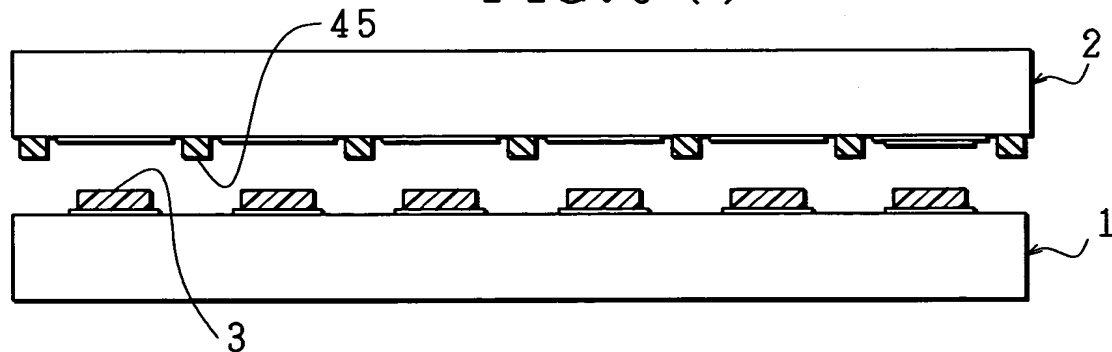
FIG. 6 (b)



$$\Delta H = H2 - H1$$

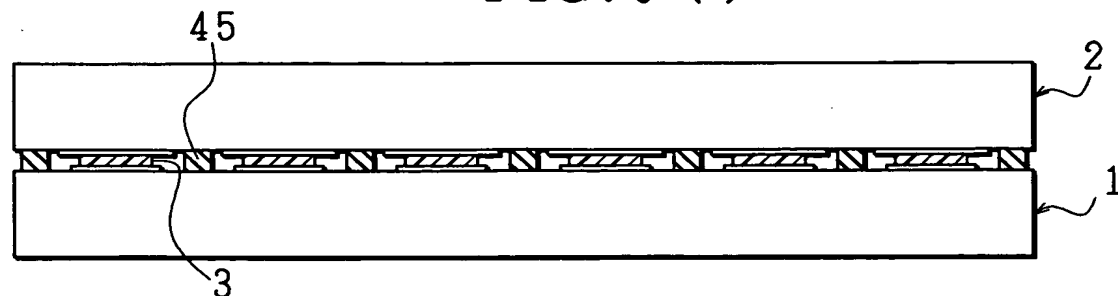
PATTERN FORMATION OF CONDUCTIVE CONNECTING MEMBERS AND SPACE KEEPING MEMBERS ON THE SUBSTRATES

FIG. 6 (c)



SUBSTRATES ARE OPPOSED TO EACH OTHER AND ALIGNED

FIG. 6 (d)



SUBSTRATES ARE BONDED TO EACH OTHER BY THERMOCOMPRESSION BONDING

FIG. 7 (a)

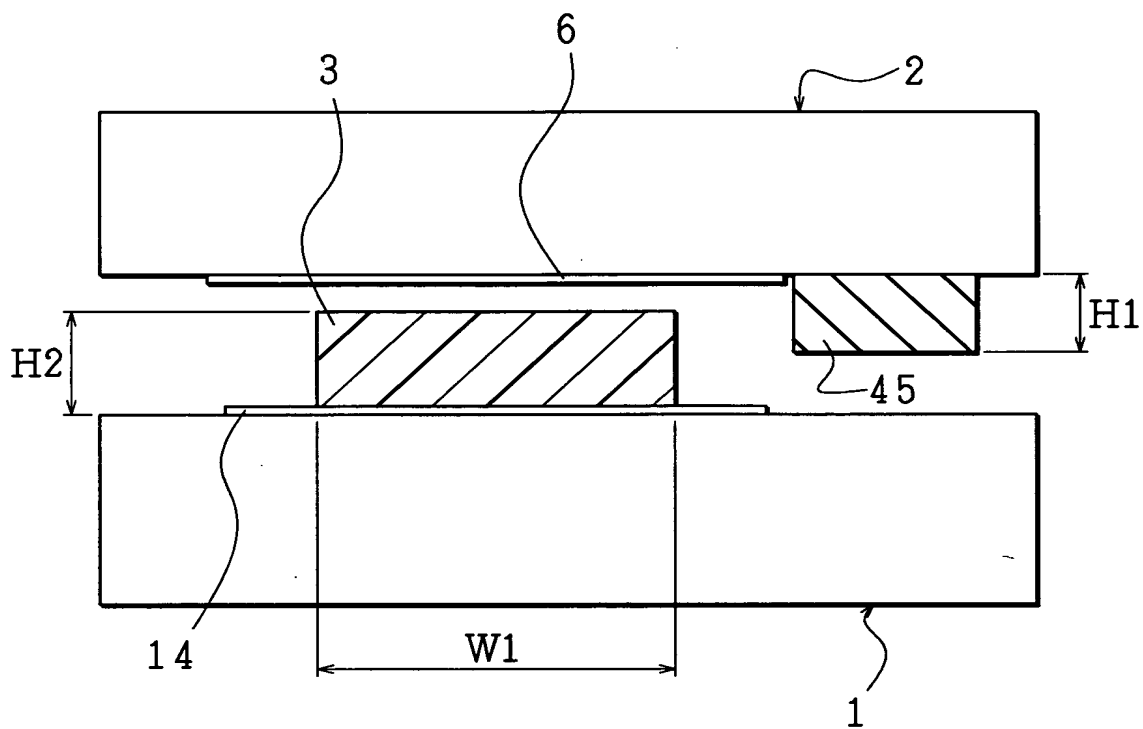


FIG. 7 (b)

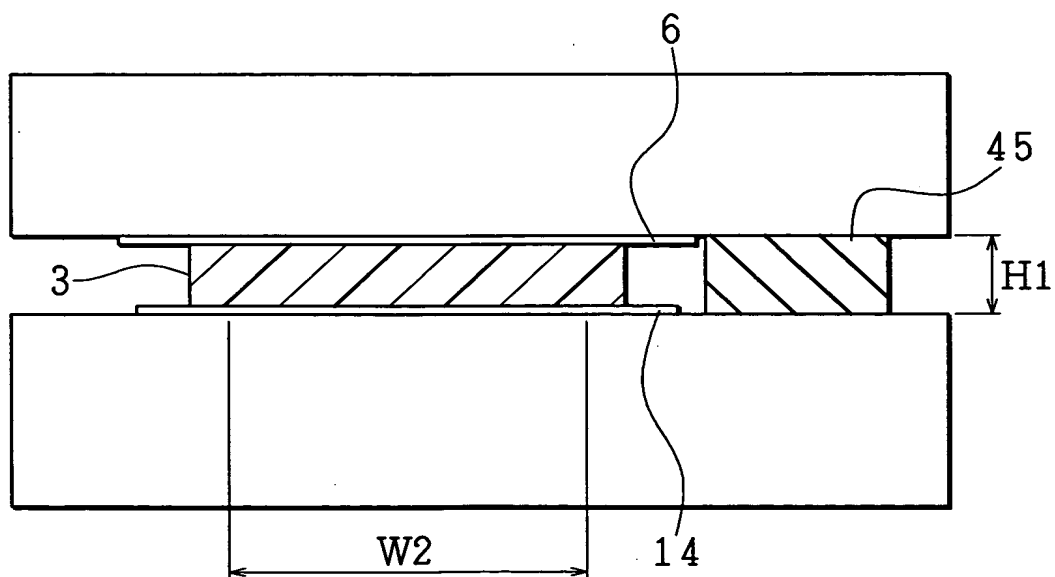


FIG. 8

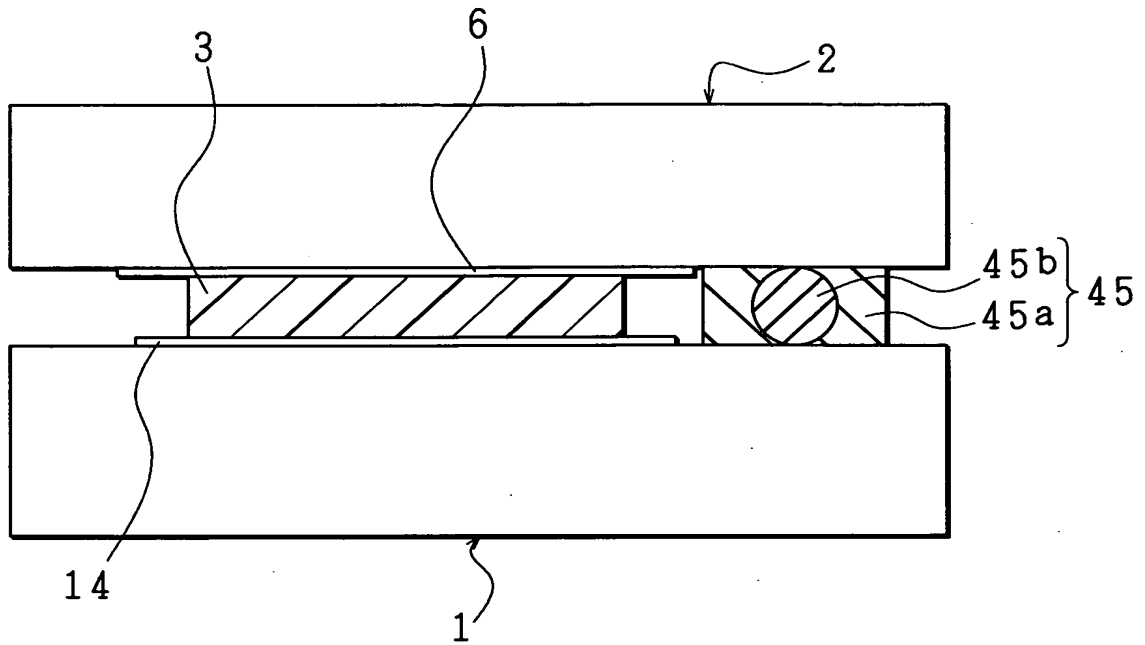


FIG. 8

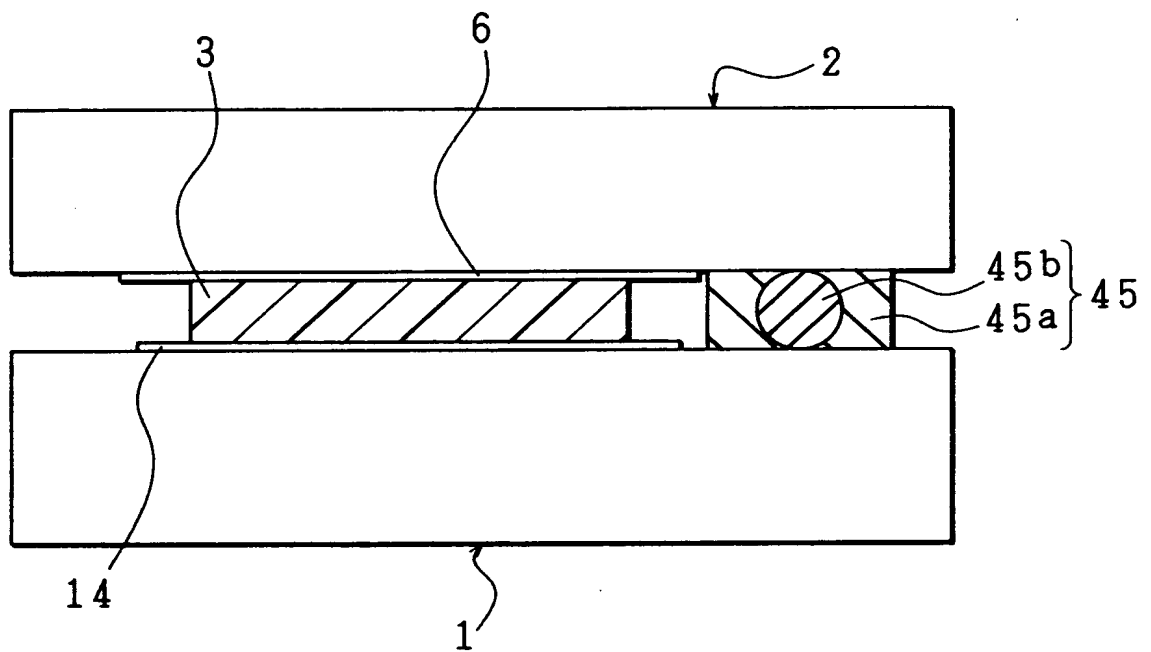


FIG. 9

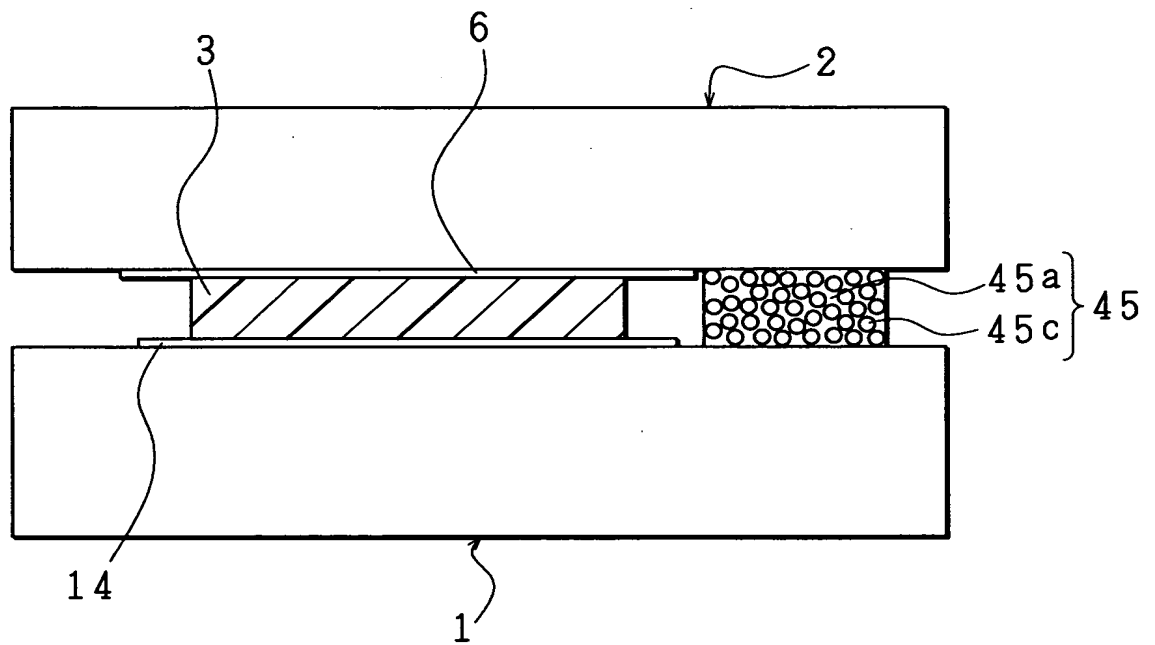


FIG. 10 (a)

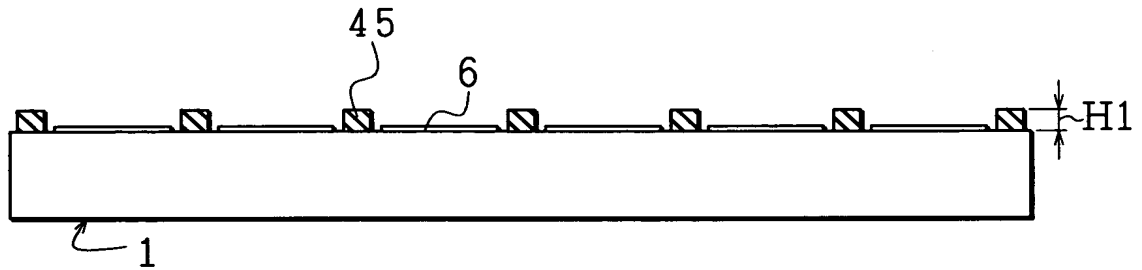
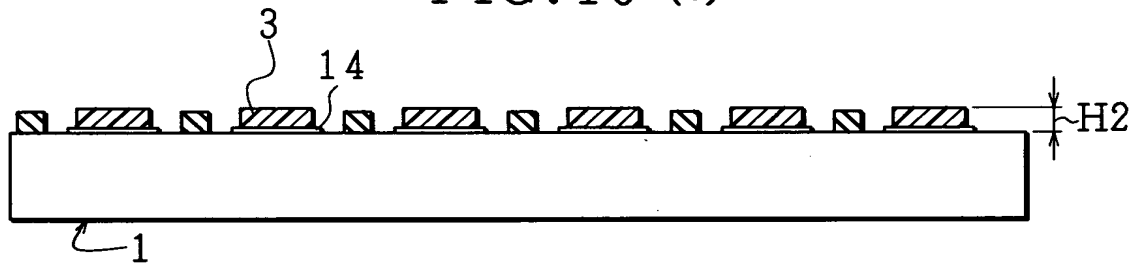


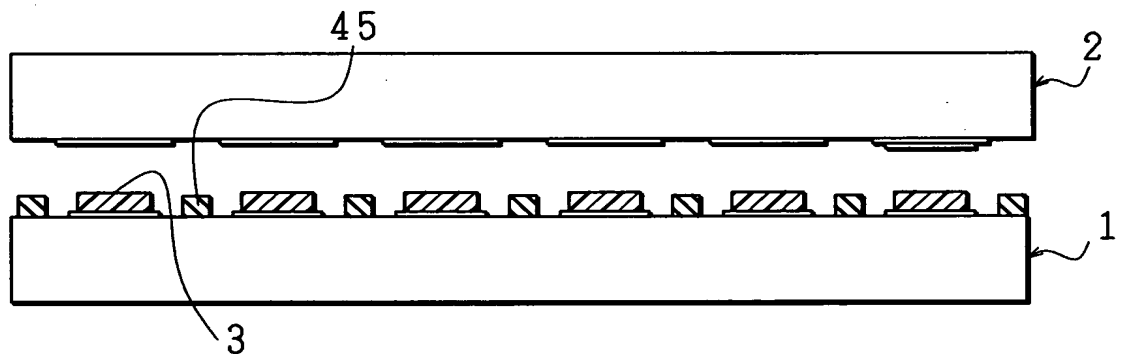
FIG. 10 (b)



PATTERN FORMATION OF CONDUCTIVE
CONNECTING MEMBERS

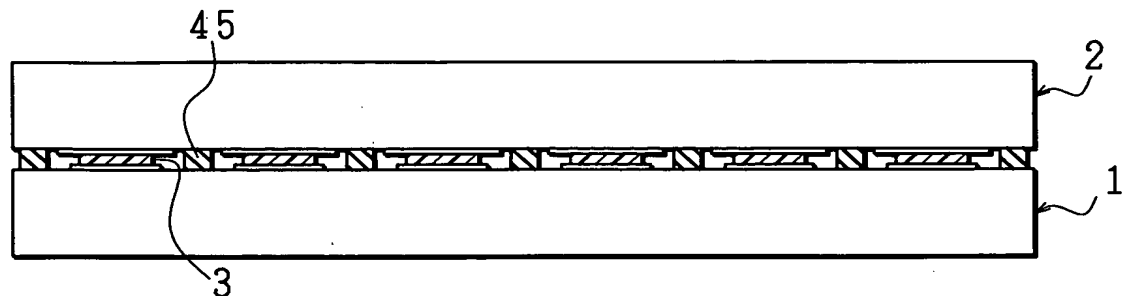
$$\Delta H = H2 - H1$$

FIG. 10 (c)



SUBSTRATES ARE OPPOSED
TO EACH OTHER AND ALIGNED

FIG. 10 (d)



SUBSTRATES ARE BONDED TO EACH OTHER
BY THERMOCOMPRESSSION BONDING

FIG.11 (a) TRANSFER STEP

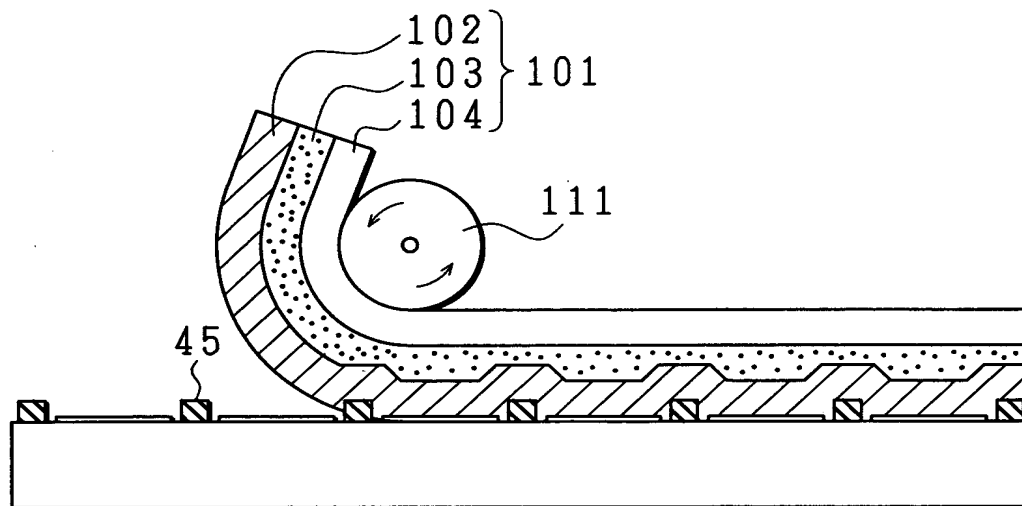


FIG.11 (b) REMOVAL OF SUPPORTING FILM

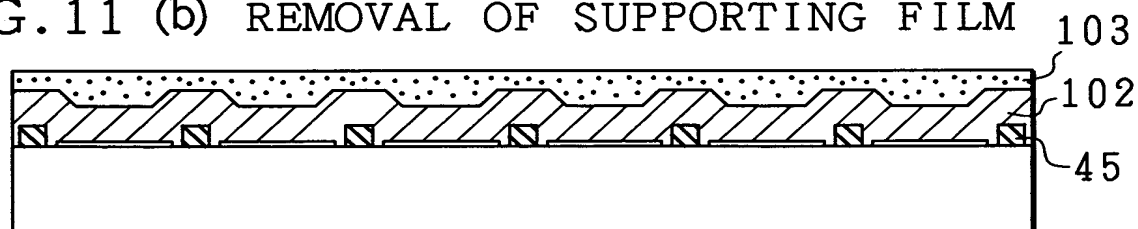


FIG.11 (c) PHOTOLITHOGRAPHY (DEVELOPING AND EXPOSING) STEP

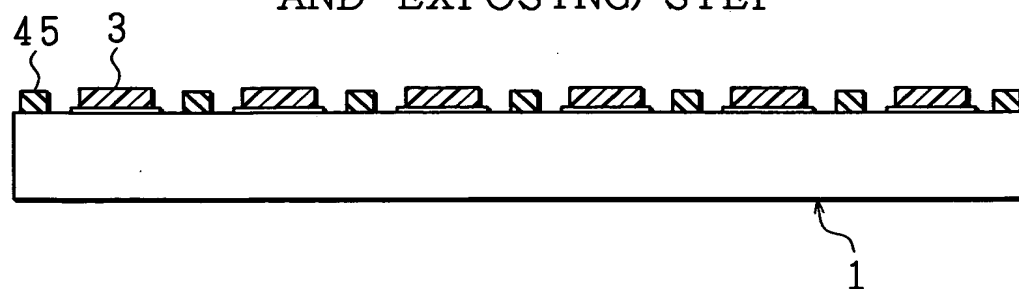
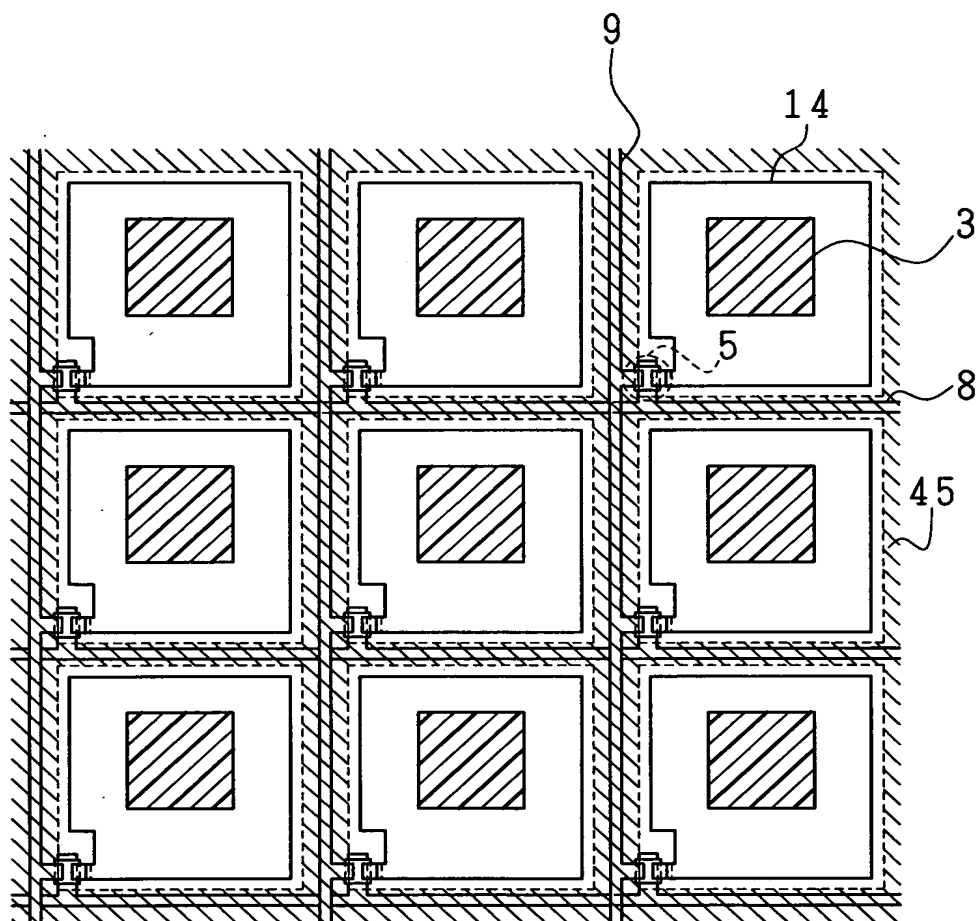
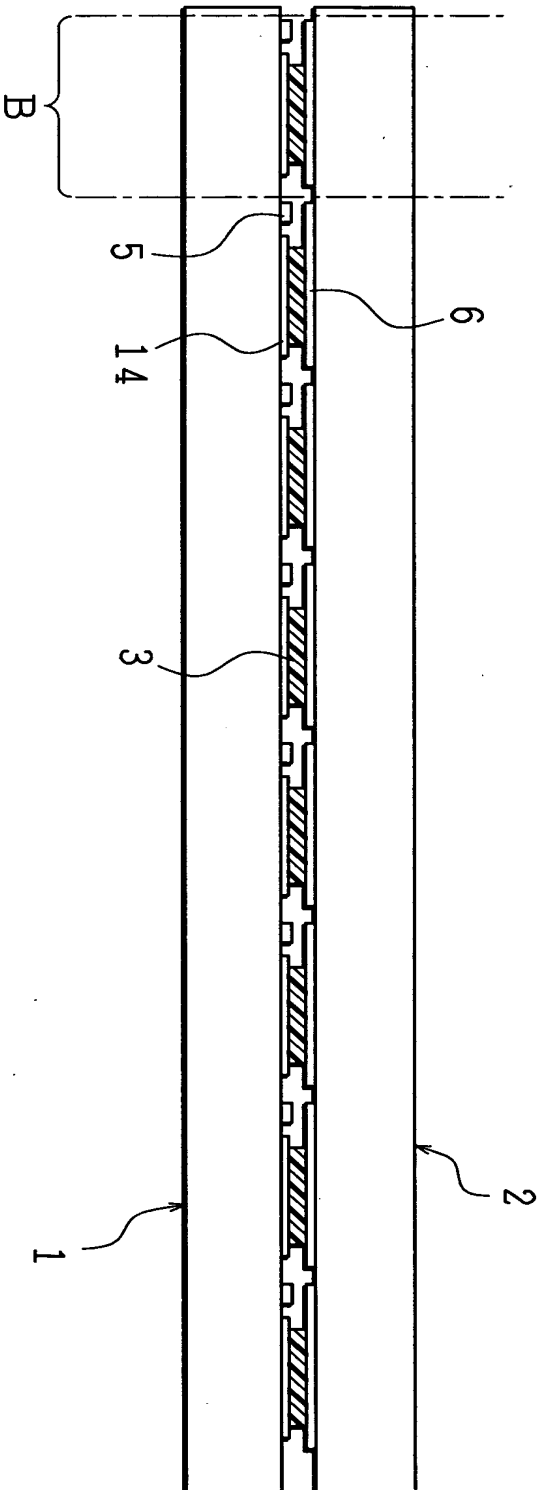


FIG. 12



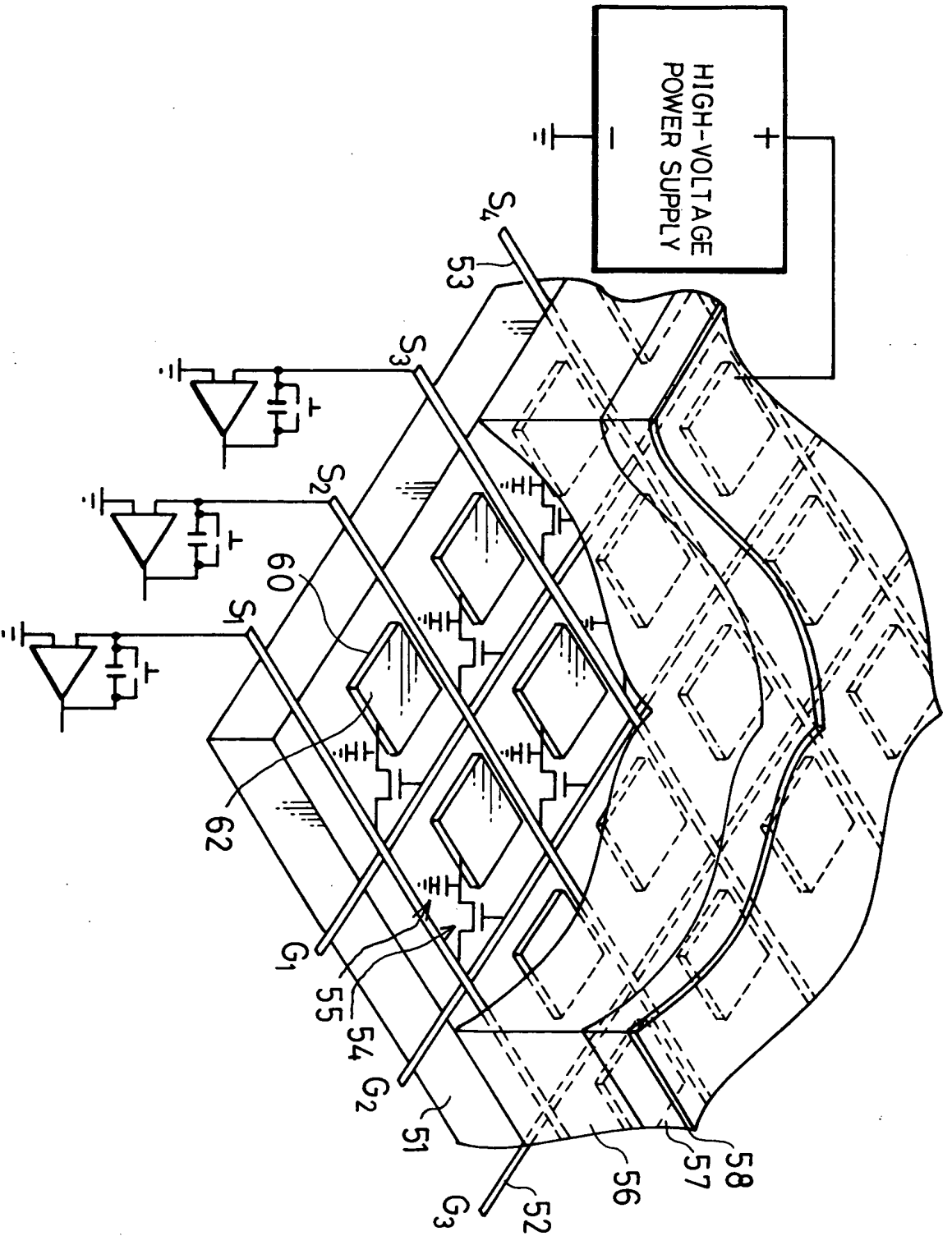
(Cs ELECTRODES 10 ARE OMITTED)

FIG. 13



[illegible]

FIG. 15



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FIG. 16

